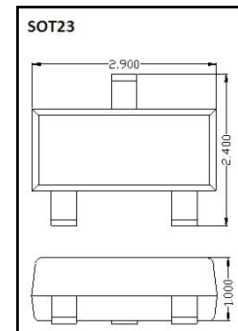


Schottky Barrier DIODE / DATA SHEET

BAS40—BAS40-06

- ◇ High Conductance
- ◇ Low Current Leakage
- ◇ Small Outline Surface Mount Package
- ◇ RoHS compliant / Green EMC

MCC Catalog Number	Device Marking	Type	Pin Configuration See page 2
BAS40	43	Single	Figure1
BAS40-04	44	Dual	Figure2
BAS40-05	45	Dual	Figure3
BAS40-06	46	Dual	Figure4

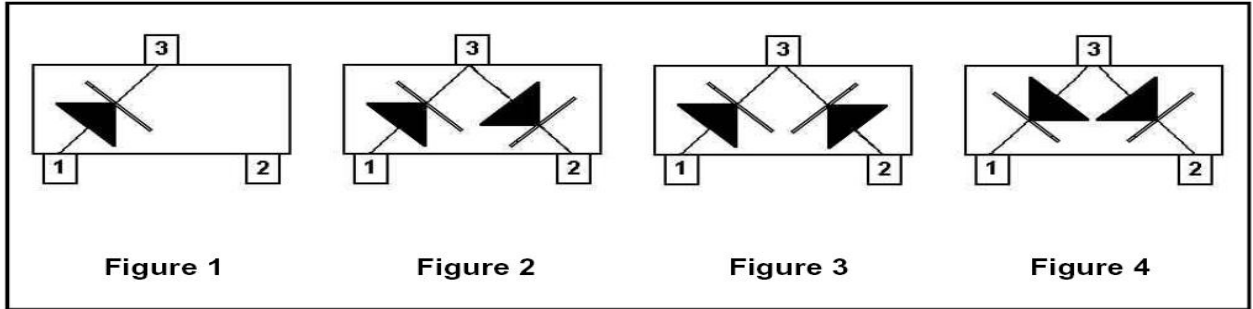


MAXIMUM RATINGS (Ta = 25 °C)

Symbol	Parameter	Value	Units
V_R	Reverse Voltage	40	V
I_F	Forward Continuous Current	200	mA
P_{tot}	Power Dissipation	200	mW
T_J	Operating Junction Temperature Range	-55 to 125	°C
I_{FSM}	Peak Forward Surge Current (t=1S.NON-Repetitive)	0.6	A
T_{stg}	Storage Temperature Rance	-55 to 150	°C
T_J	Soldering temperature during	260	°C
R_j	Thermal Resistance Junction to Ambient	500	°C/W

ELECTRICAL CHARACTERISTICS (Ta = 25 °C)

Symbol	Parameter	Test Conditions	Min	Max	Units
V_F	Forward Voltage	$I_F=1mA$ $I_F=40mA$		0.38 1.0	V
V_R	Reverse breakdown voltage	$I_R=10uA$	40		V
I_R	Reverse voltage leakage current	$V_R=30V$		200	nA
C_J	Typical Junction Capacitance	$V_R=0V, f=1.0MHz$		5	pF
T_{rr}	Reverse recovery time	$I_F=I_R=10mA, I_{(REG)}=1mA$		5	nS

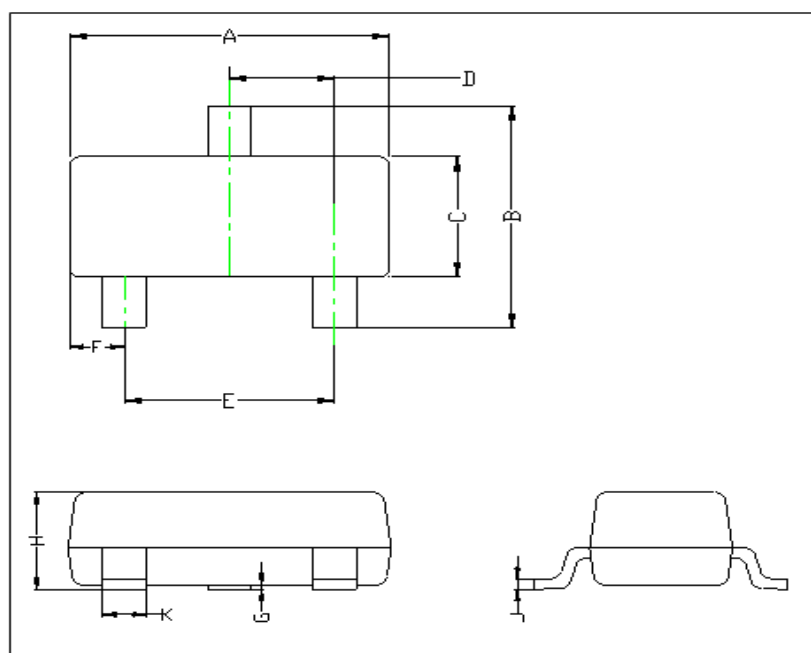


ORDERING INFORMATION

Device	Package	Shipping	Tape wide	Emboss pitch	Tape specification	Notes
BAS40---- BAS40-06	SOT23	Tape & Reel 3000pcs /7" Reel	8mm	4mm	Conductive	

PACKAGE DIMENSIONS

Package Outline : SOT23



Symbol	Dimensions in mm	
	Min.	Max.
A	2.800	3.040
B	2.100	2.640
C	1.200	1.400
D	0.890	1.030
E	1.780	2.050
F	0.450	0.600
G	0.013	0.100
H	0.900	1.110
J	0.090	0.180
K	0.370	0.510

Note:
 1. Halogen free ,EMC
 2. Pb free solder
 3: Lead thickness solder plating
 4. Lead frame CAC-5
 5. Other Tolerance ± 0.05
 6. Dimensions are exclusive of Burrs Mold Flash and Tie Bar extrusions
 7. Unit : mm

SOT23 Package Outline

NOTICE

AM'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS COMPONENTS IN ANY LIFE SUPPORT DEVICES OR SYSTEMS.

AM reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. AM does not assume any liability arising out of the application or use of any product described herein.